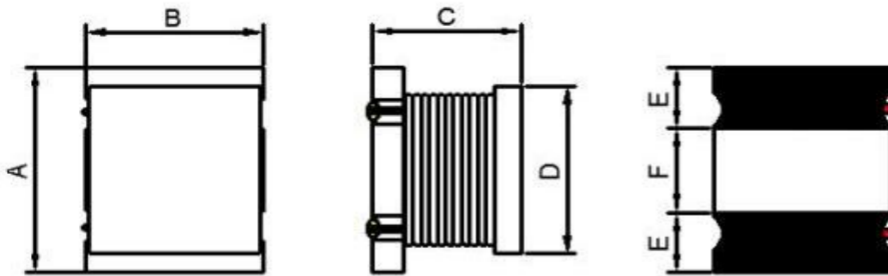


SMD Power Inductors
◆ Dimensions(Unit:mm):


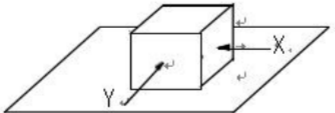
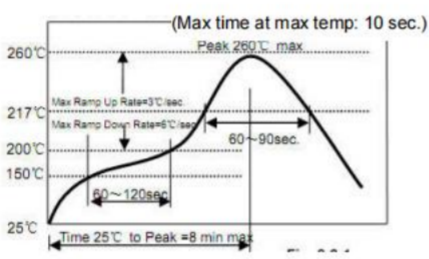
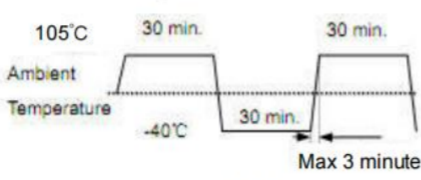
A	4.50±0.3
B	3.20±0.2
C	2.60±0.2
D	3.60±0.2
E	1.55±0.3
F	1.40±0.3

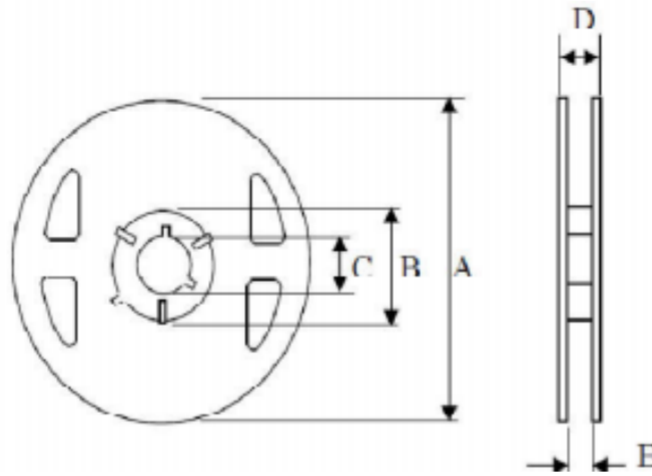
◆ Electrical Characteristics:

Part No	Inductance (μ H)	Tolerance ($\pm\%$)	Test Condition	RDC (Ω)	Idc (A)	S.R.F (MHz)
				Max	MAX	Min
SCN453226N1R0MST	1.0	20	1MHz/0.25V	0.08	1.08	100
SCN453226N2R2MST	2.2	20	1MHz/0.25V	0.11	0.90	60
SCN453226N3R3KST	3.3	20	1MHz/0.25V	0.13	0.80	47
SCN453226N4R7MST	4.7	10	1MHz/0.25V	0.15	0.75	35
SCN453226N6R8MST	6.8	20	1MHz/0.25V	0.20	0.72	30
SCN453226N100KST	10.0	10	1MHz/0.25V	0.24	0.65	23
SCN453226N150KST	15.0	10	1MHz/0.25V	0.32	0.57	20
SCN453226N330KST	33.0	10	1MHz/0.25V	1.2	0.27	11
SCN453226N470KST	47.0	10	1MHz/0.25V	1.5	0.22	9.0
SCN453226N101KST	100	10	1MHz/0.25V	2.5	0.16	6.8
SCN453226N221KST	220	10	1MHz/0.25V	5.4	0.11	4.5
SCN453226N331KST	330	10	1MHz/0.25V	8.2	0.095	3.0
SCN453226N471KST	470	10	1MHz/0.25V	11.8	0.080	2.5
SCN453226N561KST	560	10	1MHz/0.25V	14.5	0.070	2.0

※: This indicates the value of current when the inductance is 10% lower than its initial value at D.C superposition and D.C current when temperature rise $\Delta T=20^{\circ}\text{C}$. ($T_a=25^{\circ}\text{C}$)

◆ Reliability Test

Items	Requirements	Test Method/Condition
Terminal Strength	No removal or split of the termination or other defects shall occur  Fig.7.1-1	1.Solder the inductor to the testing jig (glass epoxy board shown in Fig.7.1-1) using eutectic solder. Then apply a force in the direction of the arrow. 2.10N force 3.Keep time: 5±2s
High Temperature	1.No visible mechanical damage 2.Inductance change: Within ±10%.	1.Storage Temperature :125±5°C 2.Duration : 96±4 Hours 3.Recovery : then measured at room ambient temperature after placing 24 hours.
Low Temperature	1.No visible mechanical damage 2.Inductance change: Within ±10%	1.Temperature and time: -40±5°C 2.Duration: 96±4 hours 3.Recovery : then measured at room ambient temperature after placing 24 hours
Vibration test	1.No visible mechanical damage 2.Inductance change: Within ±10%	1.Frequency range:10Hz~55Hz~10Hz 2.Amplitude:1.5mm p-p 3.Direction:X,Y,Z 4.Time:1 minute/cycle,2hours per axis
High Temperature Storage Tested	1.No visible mechanical damage. 2.Inductance change: Within ±10%	1.Storage Temperature :60±2°C 2.Relative Humidity :90-95% RH 3.Duration : 96±4 Hours 4.Recovery : then measured at room ambient temperature after placing 24 hours
Resistance to Soldering Heat	1.No visible mechanical damage 2.Inductance change: Within ±10%  Fig.7.6-1	1.Re-flowing Profile: Please refer to Fig.7.6-1 2.Test board thickness: 1.0mm 3.Test board material: glass epoxy resin 4.The chip shall be stabilized at normal condition for 1~2 hours before measuring
Thermal Shock	1.No visible mechanical damage. 2.Inductance change: Within ±10%  Fig.7.7-1	1.Temperature and time: -40±3°C for 30±3 min→ 105°C for 30±3min, please refer to Fig.7.7-1 2.Transforming interval: Max,3 minute 3.Tested cycle: 100 cycles 4.The chip shall be stabilized at normal condition for 1~2 hours before measuring

◆ Packaging


Part NO	A	B	C	D	E	Quantity
SCN453226N Series	330	60±0.8	13±0.4	16	12.5	2500Pcs/R